

D-SUB HIGH DENSITY SOLDER SOCKET CON.



8071 SERIES. D Sub High Density socket connector.

General Features

- Available in 15, 26, 44, 62 and 78 ways
- Contact area: selective gold plating over nickel
- Solder area: tin plating over nickel
- Use hood 8030, 8031, 8034, 8029 and 8027 series
- Different hardware options. Contact sales office

Materials

- Insulator: Glass-Filed Thermoplastic PBT, UL94V-0 rated
- Contact: Phosphor bronze
- Shell : Steel, 100U Tin Over 50U Min Copper
- Clinch Nut : Brass, Nickel Plated
- Screwlock : Brass, Nickel Plated
- Operating temperature. -25°C to +85°C
- RoHS compliant

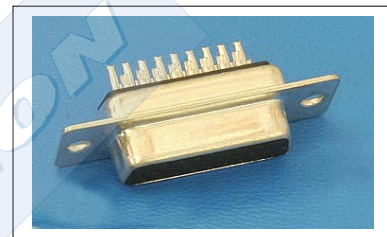
Dimension Information

Electrical Features

- Voltage rating: < 250 V
- Current rating: < 3 A
- Contact resistance: < 20 mΩ
- Dielectric withstanding Voltage: 500 V AC/minute
- Insulation resistance: >1000 MΩ

Mechanical Features

- Insertion force per contact: < 0.30 Kgf
- Withdrawal force per contact: < 0.015 Kgf
- Durability: 500 Cycles



Circuit Size	Part Number	Dimensions				
		A	B	C	D	E
15	8071 - T15C	16.33 (0.643)	24.99 (0.984)	30.81 (1.213)	19.23 (0.757)	2.290 (0.090)
26	8071 - T26C	24.66 (0.971)	33.32 (1.312)	39.14 (1.541)	27.56 (1.085)	2.290 (0.090)
44	8071 - T44C	38.38 (1.511)	47.04 (1.852)	53.04 (2.088)	41.28 (1.625)	2.290 (0.090)
62	8071 - T62C	54.84 (2.159)	63.50 (2.500)	69.32 (2.729)	57.73 (2.273)	2.410 (0.095)
78	8071 - T78C	52.43 (2.064)	61.11 (2.406)	66.93 (2.635)	55.32 (2.178)	2.410 (0.095)

T = Contact Plating

- T = 3. Gold flash over 50μ" nickel.
- T = 4. 10μ" gold over 50μ" nickel
- T = 5. 15μ" gold over 50μ" nickel
- T = 6. 30μ" gold over 50μ" nickel

C = Hardware Options

- C = 1. Standard with 3.05mm(.012") dia. mount hole
- C = 2. Version T2
- C = 4. Version D2

